TOSHIBA MOS MEMORY PRODUCTS

1024 WORD x 4 BIT STATIC RAM

TMM2114AP-12
TMM2114AP-15

DESCRIPTION

The TMM2114AP is a 4,096 bits static random access memory organized as 1024 words by 4 bits and operates from a single 5V power supply. Toshiba's high performance device technology provides both high speed and low power features with maximum operating current of 60mA and maximum access time of 120ns/150ns. The memories with 6Tr. cells are fully static in operation and require no clocks or refresh periods. Therefore the TMM2114AP is most suitable for use in microcomputer peripheral memory where high performance, lower cost, simple interfacing are required.

The TMM2114AP is fabricated with N channel silicon gate depletion load type MOS technology by ion implantation for high speed, high performance and high reliability.

The chip is moulded in the standard 18 pin plastic package with 0.3 inch width.
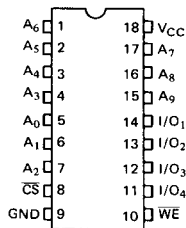
FEATURES

- 1024 Word x 4 Bit organization
- Fully static operation
- Single 5V supply voltage
- All inputs and outputs: Directly TTL compatible
- Three state output: Wired OR capability
- Common data inputs and outputs
- 2114A type pin compatible
- Fast Access time and Low Operating Current (Max.)

	TMM2114AP-12	TMM2114AP-15
$t_{ACC(ns)}$	120	150
$I_{CC(mA)}$	60	60

- Input protected: All inputs have protection against static charge.

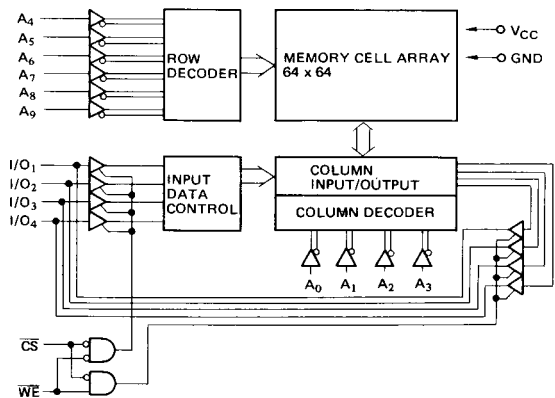## PIN CONNECTION (TOP VIEW)

A_6	1	18	V_{CC}
A_5	2	17	A_7
A_4	3	16	A_8
A_3	4	15	A_9
A_0	5	14	I/O_1
A_1	6	13	I/O_2
A_2	7	12	I/O_3
$\overline{CS}$	8	11	I/O_4
GND	9	10	$\overline{WE}$

PIN NAMES

$A_0 \sim A_3$	Column Address Inputs
$A_4 \sim A_9$	Row Address Inputs
$I/O_1 \sim I/O_4$	Data Input/Output
$\overline{CS}$	Chip Select Input
$\overline{WE}$	Write Enable Input
V_{CC}	Supply Voltage
GND	Ground

BLOCK DIAGRAM

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TRUTH TABLE

$\overline{CS}$	$\overline{WE}$	D_{IN}	D_{OUT}	MODE
H	*	*	High Impedance	Non-decode
L	H	*	Data Output	Read
L	L	H/L	Data Input	Write

* L or H

MAXIMUM RATINGS

SYMBOL	ITEM	RATING	UNIT
V_{CC}	Supply Voltage	$-0.5 \sim 7.0$	V
$V_{I/O}$	Input/Output Voltage	$-0.5 \sim 7.0$	V
T_{OPR}	Operating Temperature	$0 \sim 70$	°C
T_{STG}	Storage Temperature	$-55 \sim 150$	°C
T_{SOLDER}	Soldering Temperature · Time	$260 \cdot 10$	°C · sec
P_D	Power Dissipation (Ta = 70°C)	850	mW

DC RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V_{IH}	Input High Voltage	2.0	–	$V_{CC}+1.0$	V
V_{IL}	Input Low Voltage	-0.5	–	0.8	V
V_{CC}	Supply Voltage	4.5	5	5.5	V

DC CHARACTERISTICS (Ta = 0 ~ 70°C)

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.*	MAX.	UNIT
I_{IL}	Input Leakage Current	$V_{IN} = 0V \sim 5.5V$	-10	–	10	μA
V_{OH}	Output High Voltage	$I_{SOURCE} = -1.0mA$	2.4	–	–	V
V_{OL}	Output Low Voltage	$I_{SINK} = 2.1mA$	–	–	0.4	V
I_{LO}	Output Leakage Current	$\overline{CS} = V_{IH}$ or $\overline{WE} = V_{IL}$ $V_{OUT} = 0.0V \sim 5.5V$	-10	–	10	μA
I_{CC}	Supply Current	$I_{OUT} = 0mA$	–	–	60	mA

* Ta = 25°C, V_{CC} = 5V

AC CHARACTERISTICS (Ta = 0 ~ 70°C, V_CC = 5V ± 10%, 1-TTL Gate & C_L = 100pF, t_r, t_f ≤ 10 ns)

READ CYCLE

SYMBOL	PARAMETER	TMM2114AP-12			TMM2114AP-15			UNIT
		MIN.	TYP.*	MAX.	MIN.	TYP.*	MAX.	
t_RC	Read Cycle Time	120	–	–	150	–	–	ns
t_ACC	Access Time	–	–	120	–	–	150	ns
t_CO	Chip Select Time	–	–	70	–	–	70	ns
t_CX	Output Active from CS̄	10	–	–	10	–	–	ns
t_OD	Deselect Time	0	–	35	0	–	40	ns
t_OH	Output Hold From Address Change	20	–	–	20	–	–	ns

* Ta = 25°C, V_CC = 5V

WRITE CYCLE

| SYMBOL	PARAMETER	TMM2114AP-12			TMM2114AP-15			UNIT
		MIN.	TYP.*	MAX.	MIN.	TYP.*	MAX.	
t_WC	Write Cycle Time	120	–	–	150	–	–	ns
t_WP	Write Pulse Width	70	–	–	90	–	–	ns
t_WR	Write Recovery Time	0	–	–	0	–	–	ns
t_ODW	Output High Z From W̄Ē	0	–	35	0	–	40	ns
t_DS	Data Setup Time	70	–	–	90	–	–	ns
t_DH	Data Hold Time	0	–	–	0	–	–	ns
t_AW	Address to Write Setup Time	0	–	–	0	–	–	ns

* Ta = 25°C, V_CC = 5V

CAPACITANCE (Ta = 25°C, f = 1MHz)

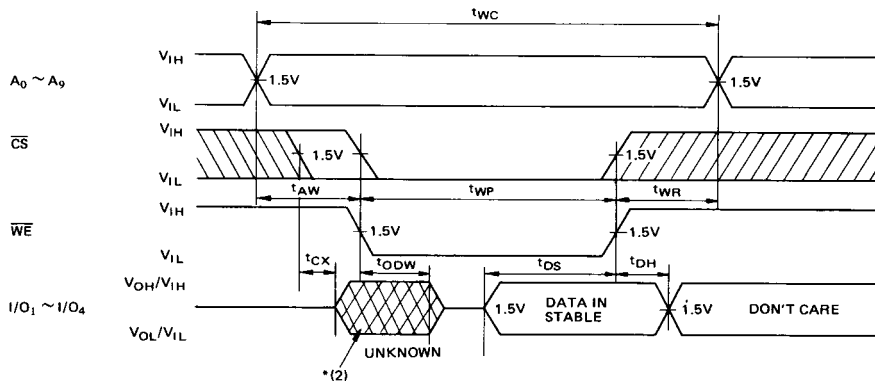| SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
C_IN	Input Capacitance	V_IN = AC Ground	–	–	5	pF
C_OUT	Output Capacitance	V_OUT = AC Ground	–	–	10	pF

Note: This parameter is periodically sampled and not 100% tested.

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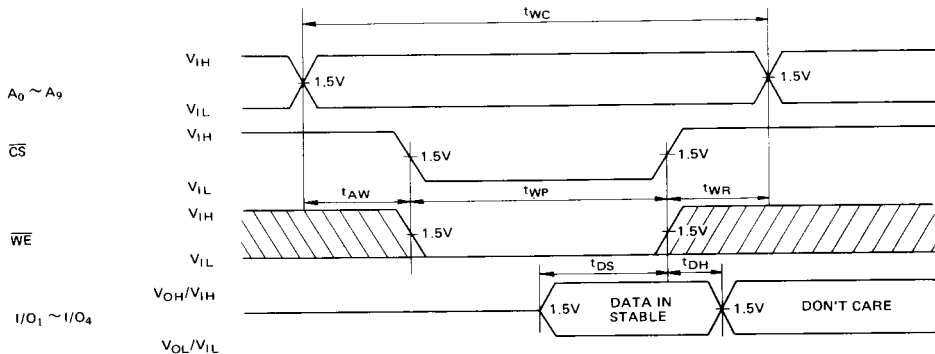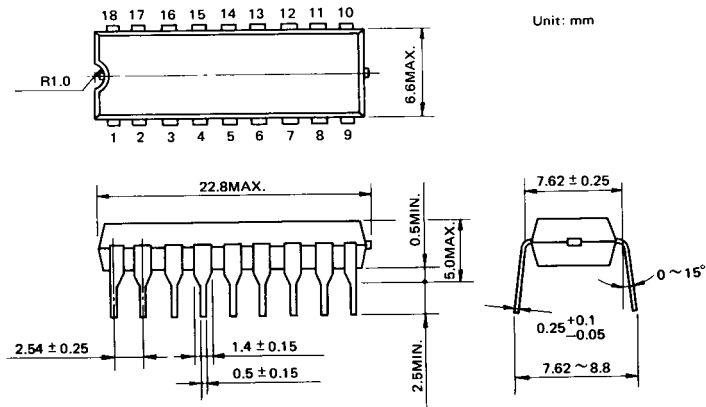## TIMING WAVEFORMS

● READ CYCLE

● WRITE CYCLE [1] *(1)

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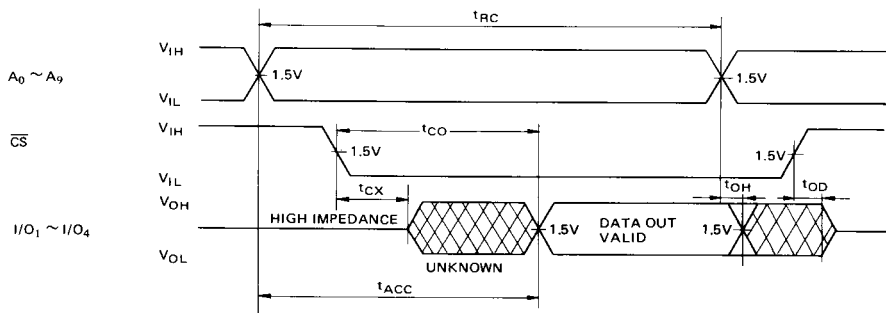
● WRITE CYCLE [2] *(1)

Note *(1): A write occurs during the overlap of a low $\overline{CS}$ and low $\overline{WE}$.
And twp is specified as the logical 'AND' of $\overline{CS}$ and $\overline{WE}$.
*(2): If the $\overline{CS}$ low transition occurs simultaneously with or latter from $\overline{WE}$ low transition, the output buffers remain in a high impedance state in this period.

OUTLINE DRAWINGS

Unit: mm

Note: All dimensions are in millimeters. Each lead pitch is 2.54mm.
All leads are located within 0.25mm of their true longitudinal position with respect to No. 1 and No. 18 leads.